Tool ID: 315
Tool Location: 115

Equipment Information Sheet

Polaron Gold Sputtering System

Manager: Philip Schneider 607-254-4931
Backup: John Treichler 607-254-4949
Backup: Xinwei Wu 607-254-4934

Calls to staff phones will be automatically forwarded to their cell phones during accessible hours. At other times leave a message or send them an email.

SAFETY

- DO NOT attempt operation with the vacuum chamber lid open!

USAGE RESTRICTIONS

- No depositions longer than 3 minutes

SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 0 minutes

- None

MATERIALS COMPATIBILITY CATEGORY

Tool Category 5: Class A and B Metals and Compounds

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared-w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

Additional Material Restrictions and Exceptions

- Only for use on materials going into the SEM or e-beam lithography systems.

Last Updated: 06/09/2025